



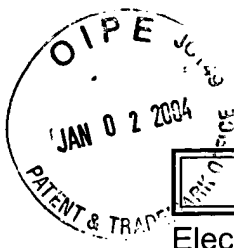
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Electronic Patent Application Submission  
USPTO Use Only

EFS ID: 53065  
Application ID: 10669820  
Title of Invention: REINFORCED DIE PAD SUPPORT  
STRUCTURE  
First Named Inventor: Chung Tzu  
Domestic/Foreign Application: Domestic Application  
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Confirmation number: 5197  
Attorney Docket Number: AMKOR090




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Office,ou=Department of Commerce,o=U.S. Government,c=US  
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**TRANSMITTAL**

Electronic Version v1.1  
Stylesheet Version v1.1.0

<b>Title of Invention</b>	<b>REINFORCED DIE PAD SUPPORT STRUCTURE</b>									
<p>Application Number: 10/669820 </p> <p>Date: 2003-09-24</p> <p>First Named Applicant: Chung Hsing Tzu</p> <p>Confirmation Number: 5197</p> <p>Attorney Docket Number: AMKOR090</p>										
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Mark B. Garred Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Mark B. Garred Registered Number: 34,823	/mbg/	Attorney		
Submitted by:	Elec. Sign.	Sign. Capacity								
Mark B. Garred Registered Number: 34,823	/mbg/	Attorney								
<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>ids1-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	ids1-usidst.xml		us-ids.dtd		us-ids.xsl
Documents being submitted	Files									
us-ids	ids1-usidst.xml									
	us-ids.dtd									
	us-ids.xsl									
<b>Comments</b>										



# ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of  
Invention

REINFORCED DIE PAD SUPPORT STRUCTURE

Application Number: 10/669820



Confirmation Number: 5197

First Named Applicant: Chung Tzu

Attorney Docket Number: AMKOR090

Art Unit: 2811

Search string: ( 2596993 or 3435815 or 3734660 or 3838984  
or 4054238 or 4189342 or 4258381 or 4289922  
or 4301464 or 4332537 or 4417266 or 4451224  
or 4530152 or 4541003 or 4646710 or 4707724  
or 4727633 or 4737839 or 4756080 or 4812896  
or 4862245 or 4862246 or 4907067 or 4920074  
or 4935803 or 4942454 or 4987475 or 5018003  
or 5029386 or 5041902 or 5057900 or 5059379  
or 5065223 or 5070039 or 5087961 or 5091341  
or 5096852 or 5118298 or 5151039 or 5157475  
or 5157480 or 5168368 or 5172213 or 5172214  
or 5175060 or 5200362 or 5200809 or 5214845  
or 5216278 or 5218231 or 20010008305 or  
20010014538 or 20010011654 or 20020024122  
or 20020027297 or 20020140061 or  
20020140068 or 20020163015 or 20030030131  
or 20030073265 ),pn.

## US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	2596993	1952-05-20	S.L. GOOKIN			
	2	3435815	1969-04-01	FORCIER			
	3	3734660	1973-05-22	DAVIES ET AL.			
	4	3838984	1974-10-01	CRANE ET AL.			
	5	4054238	1977-10-18	LLOYD ET AL.			
	6	4189342	1980-02-19	KOCK			
	7	4258381	1981-03-24	INABA			

	8	4289922	1981-09-15	DEVLIN
	9	4301464	1981-11-17	OTSUKI ET AL.
	10	4332537	1982-06-01	SLEPCEVIC
	11	4417266	1983-11-22	GRABBE
	12	4451224	1984-05-29	HARDING
	13	4530152	1985-07-23	ROCHE ET AL.
	14	4541003	1985-09-10	OTSUKA ET AL.
	15	4646710	1987-04-03	SCHMID ET AL.
	16	4707724	1987-11-17	SUZUKI ET AL.
	17	4727633	1988-03-01	HERRICK
	18	4737839	1988-04-12	BURT
	19	4756080	1988-07-12	THORP, JR. ET AL.
	20	4812896	1989-03-14	ROTHGERY ET AL.
	21	4862245	1989-08-29	PASHBY ET AL.
	22	4862246	1989-08-29	MASUDA ET AL.
	23	4907067	1990-03-06	DERRYBERRY
	24	4920074	1990-04-24	SHIMIZU ET AL.
	25	4935803	1990-06-19	KALFUS ET AL.
	26	4942454	1990-07-17	MORI ET AL.
	27	4987475	1991-01-22	SCHLESINGER ET AL.
	28	5018003	1991-05-21	YASUNAGA ET AL.
	29	5029386	1991-07-09	CHAO ET AL.
	30	5041902	1991-08-20	MCSHANE
	31	5057900	1991-10-15	YAMAZAKI
	32	5059379	1991-10-22	TSUTSUMI ET AL.
	33	5065223	1991-11-12	MATSUKI ET AL.
	34	5070039	1991-12-03	JOHNSON ET AL.
	35	5087961	1992-02-11	LONG ET AL.
	36	5091341	1992-02-25	ASADA ET AL.
	37	5096852	1992-03-17	HOBSON
	38	5118298	1992-06-02	MURPHY
	39	5151039	1992-09-29	MURPHY
	40	5157475	1992-10-20	YAMAGUCHI
	41	5157480	1992-10-20	MCSHANE ET AL.
	42	5168368	1992-12-01	GOW, 3RD ET AL.
	43	5172213	1992-12-15	ZIMMERMAN

	44	5172214	1992-12-15	CASTO
	45	5175060	1992-12-29	ENOMOTO ET AL.
	46	5200362	1993-04-06	LIN ET AL.
	47	5200809	1993-04-06	KWON
	48	5214845	1993-06-01	KING ET AL.
	49	5216278	1993-06-01	LIN ET AL.
	50	5218231	1993-06-08	KUDO

## US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20010008305	2001-07-19	MCLELLAN ET AL.			
	2	20010014538	2001-08-16	KWAN ET AL.			
	3	20010011654	2002-01-31	KIMURA			
	4	20020024122	2002-02-28	JUNG ET AL.			
	5	20020027297	2002-03-07	IKENAGA ET AL.			
	6	20020140061	2002-10-03	LEE			
	7	20020140068	2002-10-03	LEE ET AL.			
	8	20020163015	2002-11-07	LEE ET AL.			
	9	20030030131	2003-02-13	LEE ET AL.			
	10	20030073265	2003-04-17	HU ET AL.			

Signature

Examiner Name	Date